



Session Title:	[MA1] Advanced Atomic Scale Thin Films I
Session Date:	November 20 (Mon.), 2023
Session Time:	13:00-14:40
Session Room:	Room A (Capri Room, 2F)
Session Chair:	Prof. Hyeongtag Jeon (Hanyang Univ., Korea)

[MA1-1] [Invited] 13:00-13:30

Development of Material Systems and Processes for Highly-Reliable ULSI-Cu Interconnect

Yukihiro Shimogaki (The Univ. of Tokyo, Japan)

[MA1-2] [Invited] 13:30-14:00

The Advancements of Atomic Scale Interface Engineering for High Quality Dielectric Thin Films

Chunhyung Chung, Yongsuk Tak, Wonseok Yoo, Deayoung Moon, Kyoungwook Park (Samsung Electronics Co., Ltd., Korea)

[MA1-3] [Invited] 14:00-14:20

Spontaneous Surface Reactions in Atomic Layer Deposition of Platinum Using Atomic Hydrogen as a Reactant

Huong Thi Thuy Ta, Ngoc Linh Nguyen, and Hao Van Bui (Phenikaa Univ., Vietnam)

[MA1-4] [Invited] 14:20-14:40

Pt Thin Films by Atomic Layer Deposition Using Dimethyl(N,N-Dimethyl-3-Buten-1-Amine-N) Platinum and O₂ Reactant towards the Semiconductor Application

Woo-Jae Lee (Pukyong Nat'l Univ., Korea)